## Discontinuation Notification

202102018DN : Non-Auto i.MX53 PBGA Part Number Migration due to Molding Change from Corner-Gate Mold (CGM) to Pin-Gate Mold (PGM)

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Feb 20, 2021 **Effective date:**Feb 21, 2021

# PCN Overview

## Discontinuation Information

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As previously mentioned in Advanced PCN 202010043A, NXP is announcing the conversion from Corner-Gate Mold (CGM) process platform to Pin-Gate Mold (PGM) process platform for the devices listed in this notification.

The change from Corner-Gate Mold (CGM) process to Pin-Gate Mold (PGM) process is driven by NXP assembly subcontractor Amkor Korea announcing it will phase out CGM (Corner-Gate mold) PBGA assembly platform by late June 2021, and production support will be continued with PGM (Pin-Gate mold) PBGA process thereafter. CGM PBGA process platform capacity has been contracting due to the transition to PGM process platform.

To support the transition to Pin-Gate Mold (PGM) process, this Discontinuance Notification is being issued with new replacement part numbers and qualification results for Pin-Gate Mold (PGM) process. New replacement part numbers are required as devices will have a new case outline. Note: There are no dimensional changes to the package; new case outline is required due to change of physical appearance and part marking format only.

Please refer to details of change and qualification results attached. Note: Package identifier will change in the orderable part number (i.e. "VV" will be replaced by "VP").

Due to the unprecedented supply constraints within the Semiconductor Industry and existing backlog profile, new orders must be placed on the new replacement parts.
There are cases that existing backlog will need to be migrated to the replacement parts. NXP will work

with each customer to manage those transitions.

For orders transition timing, please contact your local sales or distribution representative.

NOTWITHSTANDING ANY STATEMENT TO THE CONTRARY CONTAINED IN THIS DISCONTINUATION NOTICE, THERE WILL BE NO OPPORTUNITY TO PLACE A FINAL LIFETIME PURCHASE.

Pin-Gate Mold Sample Part Numbers:
PCIMX535DVP1C2
PCIMX535DVP2C2
PCIMX537CVP8C2
Note: These parts are marked as Prototype, but went through the fully qualified production flow.

This Discontinuation Notice confirms to your company that NXP Semiconductors (NXP) is now discontinuing the manufacture of a number of its integrated circuits and discrete semiconductors listed in the Part Type Affected list included with this notification. In accordance with NXP product discontinuation policy and JEDEC EIA/JESD48, we are hereby giving notice of these product changes so that our customers and partners can adjust their product purchasing records, or make any final lifetime purchases of the discontinued products that can still be supplied by NXP.

While this Discontinuation Notice contains a number of NXP discontinued end-of-life Product Types, the Part Types Affected (PTA) list represents a small percentage of NXP overall semi-conductors product portfolio. Some of these discontinued products have had little to no recent sales history or they are at the end-of-life (EOL) stage. The PTA list may also cover a number of versions or selections of the same basic Product Type.

We regret the inconvenience and impact this notice may cause. NXP Semiconductors' sales, marketing and distribution personnel stand ready to assist you in placing our customers and partners's final orders, or in providing product information you require. On behalf of NXP Semiconductors, we appreciate your understanding and assistance in helping us to help you minimize the impact of this product discontinuation on your company. We look forward to NXP Semiconductors' continued support of your company's semiconductor requirements in the years to come.

## Reason for Discontinuance

Assembly subcontractor Amkor converting from Corner-Gate Mold (CGM) process to Pin-Gate Mold (PGM) process. Pin-Gate Mold (PGM) process to be qualified as assurance of supply.

## Additional information

Additional documents: view online

## Related Notification

| Notification | Issue Date | Effective Date | Title |
|---|---|---|---|
| 202010043A | Nov 19, 2020 |  | i.MX53 PBGA Product Molding Change from Corner-Gate Mold(CGM) to Pin-Gate Mold(PGM) |

**About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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